2 3	mber	26 26 2043	Search Text   ("6594542" "6531399" "6494765" "6439964" "2	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	Time stamp "800440099046047945" "6
3			friction near3 (sensor sensors sensing	EPO; JPO; DERWENT; IBM_TDB	
3			friction near3 (sensor sensors sensing	DERWENT; IBM_TDB	
3			friction near3 (sensor sensors sensing	IBM_TDB	
3			friction near3 (sensor sensors sensing	_	
3			Ifficion hears (sensor sensors sensing	USPAT;	2004/08/04 07:55
			senses (strain adj gauge))	US-PGPUB;	2004/08/04 07.33
			deliber (belain ad) gaage,,	EPO; JPO;	
				DERWENT;	
				IBM_TDB	
4		4	(		2607408904"684097 5" '
4			and (friction near3 (sensor sensors	US-PGPUB;	
4			sensing senses (strain adj gauge)))	EPO; JPO; DERWENT;	
4				IBM TDB	
_		2705284	wafer wafers substrate substrates	USPAT;	2004/08/04 08:01
			semiconductor semiconductors	US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
_				IBM_TDB	
6		176	, , = = = : : = : : : : : : : : : : : :	USPAT;	2004/08/04 08:02
			senses (strain adj gauge))) same (wafer wafers substrate substrates semiconductor	US-PGPUB; EPO; JPO;	
			semiconductors )	DERWENT;	
			Schileonauctors /	IBM TDB	
8		363	(friction near3 (sensor sensors sensing	USPĀT;	2004/08/04 08:02
-			senses (strain adj gauge))) and (wafer	US-PGPUB;	· · ·
			wafers substrate substrates semiconductor	EPO; JPO;	
			semiconductors )	DERWENT;	
_				IBM_TDB	
7		139	(friction near3 (sensor sensors sensing	USPAT;	2004/08/04 08:03
			senses (strain adj gauge))) with (wafer wafers substrate substrates semiconductor	US-PGPUB; EPO; JPO;	
			semiconductors )	DERWENT;	
			Semiconductors /	IBM TDB	ł
9		15464	(distance gap) adj (sensor sensors sensing	USPAT;	2004/08/04 08:19
			sensed)	US-PGPUB;	j
				EPO; JPO;	
				DERWENT;	
10		2	//frigtion near? /gencer gencers gencing	IBM_TDB USPAT;	2004/08/04 08:10
10	ĺ	2	((friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer	US-PGPUB;	2004/08/04 08:10
			wafers substrate substrates semiconductor	EPO; JPO;	İ
			semiconductors )) and ((distance gap) adj	DERWENT;	
			(sensor sensors sensing sensed))	IBM_TDB	
11		2336107	gap distance	USPAT;	2004/08/04 08:10
				US-PGPUB;	
				EPO; JPO;	ļ
				DERWENT; IBM TDB	1
12	1	3	((("6594542" "6531399" "6494765" "6439964"		"2063708704106342975"1
	Ì	J	and (friction near3 (sensor sensors	US-PGPUB;	,
	-		sensing senses (strain adj gauge)))) and	EPO; JPO;	
	1		(gap distance)	DERWENT;	İ
	1			IBM_TDB	0004/00/55 55
13		719	(wafer wafers substrate substrates	USPAT;	2004/08/04 08:12
	1		semiconductor semiconductors ) same	US-PGPUB; EPO; JPO;	
	-		((distance gap) adj (sensor sensors sensing sensed))	DERWENT;	
	1			IBM TDB	
14		363909	abrasive abrade abrading abrades abrasives	USPĀT;	2004/08/04 08:13
		•	polish polishes polished polishing	US-PGPUB;	
			polisher polishers	EPO; JPO;	
	1			DERWENT;	
1.5				IBM_TDB	0004/00/04 05 15
15		19	((wafer wafers substrate substrates semiconductor semiconductors ) same	USPAT;	2004/08/04 08:13
_			semiconductor semiconductors	US-PGPUB; EPO; JPO;	
			((distance gap) adj (sensor sensors   sensing sensed))) same (abrasive abrade	DERWENT;	
			abrading abrades abrasives polish polishes	IBM TDB	
			polished polishing polisher polishers)		

16	2	(((wafer wafers substrate substrates	USPAT;	2004/08/04 08:15
	1	semiconductor semiconductors ) same	US-PGPUB;	
		((distance gap) adj (sensor sensors	EPO; JPO;	
	1	sensing sensed))) same (abrasive abrade	DERWENT;	
	1	abrading abrades abrasives polish polishes	IBM_TDB	
		polished polishing polisher polishers))		
		and (friction near3 (sensor sensors		
		sensing senses (strain adj gauge)))		0004/00/04 00 10
21	106394	(distance gap) with (sensor sensors	USPAT;	2004/08/04 08:19
		sensing sensed)	US-PGPUB;	
			EPO; JPO;	•
	j		DERWENT;	
			IBM_TDB	
24	19	· · · · · · · · · · · ·	USPAT;	2004/08/04 08:33
		senses (strain adj gauge))) with (wafer	US-PGPUB;	
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors )) and ((distance gap) with	DERWENT;	
		(sensor sensors sensing sensed))	IBM_TDB	0001/00/01 00 05
25	4509	(wafer wafers substrate substrates	USPAT;	2004/08/04 08:25
		semiconductor semiconductors ) with	US-PGPUB;	
		((distance gap) with (sensor sensors	EPO; JPO;	
		sensing sensed))	DERWENT;	
			IBM_TDB	0004/00/01 == 1=
26	92	1 , ,	USPAT;	2004/08/04 08:25
		semiconductor semiconductors ) with	US-PGPUB;	
		((distance gap) with (sensor sensors	EPO; JPO;	
		sensing sensed))) and (strain adj gauge)	DERWENT;	
			IBM_TDB	<u> </u>
27	13	((wafer wafers substrate substrates	USPAT;	2004/08/04 08:25
		semiconductor semiconductors ) with	US-PGPUB;	
		((distance gap) with (sensor sensors	EPO; JPO;	1
		sensing sensed))) and (friction near3	DERWENT;	1
		(sensor sensors sensing senses (strain adj	IBM_TDB	1
		gauge)))	_	
28	66948	dummy	USPAT;	2004/08/04 08:30
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
29	12163	dummy with (wafer wafers substrate	USPAT;	2004/08/04 08:32
		substrates semiconductor semiconductors )	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
30	7	(dummy with (wafer wafers substrate	USPAT;	2004/08/04 08:31
		substrates semiconductor semiconductors ))	US-PGPUB;	
	ł	and (friction near3 (sensor sensors	EPO; JPO;	i
		sensing senses (strain adj gauge)))	DERWENT;	
			IBM TDB	
31	15002	dummy same (wafer wafers substrate	USPAT;	2004/08/04 08:32
		substrates semiconductor semiconductors )	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
32	3	((friction near3 (sensor sensors sensing	USPĀT;	2004/08/04 08:33
		senses (strain adj gauge))) with (wafer	US-PGPUB;	
		wafers substrate substrates semiconductor	EPO; JPO;	
		semiconductors )) and (dummy same (wafer	DERWENT;	1
		wafers substrate substrates semiconductor	IBM TDB	
		semiconductors ))		
33	3255821	condition conditioner conditioning	USPAT;	2004/08/04 08:33
	3233321	conditions conditioners	US-PGPUB;	= = = = = = = = = = = = = = = = = = =
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
34	3555	(dummy with (wafer wafers substrate	USPAT;	2004/08/04 08:34
7.3	3333	substrates semiconductor semiconductors ))	US-PGPUB;	2004/00/04 00.54
		and (condition conditioner conditioning	EPO; JPO;	
		and (condition conditioner conditioning   conditions conditioners)	DERWENT;	
	1	CONGILIONS CONGILIONEIS)		1
			IBM TDB	L

35	497	<pre>(dummy with (wafer wafers substrate substrates semiconductor semiconductors )) with (condition conditioner conditioning conditions conditioners)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/04 08:34
36	32	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/04 08:35
37	96	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 08:35
38	64	(((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.) not ((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:38
39	1140	451/6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:29
41	235	((friction torque) same (distance gap) same (sensor sensors sensing senses sense)) and(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:31
42	32	((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:32
43	3	(((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)) and (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:38
44	2664	,	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
45	285	(condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
46	0	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors ))) with arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
47	1	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors ))) same arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:39
49	0	(((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors ))) and 451/\$.ccls.) and wheels	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 09:40

2004/08/04 09:41					
Wafer wafers substrate substrates   Sept. JPO:   Semiconductors   Semiconductors   Sept. JPO:   DERNEMT:   Semiconductors   Sept. JPO:   DERNEMT:   Sept. JPO:   DERNEMT:   Sept. JPO:   DERNEMT:   Sept. JPO:   DERNEMT:   Semiconductors   Sept. JPO:   DERNEMT:   Sept. J	48	26	((condition conditioner conditioning		2004/08/04 09:41
Semiconductor semiconductors			conditions conditioners) with (dummy adj	US-PGPUB;	1
155624   155624   "L-shaped"   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:42   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 09:45   2004/08/04 10:11   2004/08/04 10:11   2004/08/04 10:11   2004/08/04 10:11   2004/08/04 10:11   2004/08/04 10:11   2004/08/04 10:12   2004/08/04 10:13			(wafer wafers substrate substrates	EPO; JPO;	
155624			semiconductor semiconductors ))) and	DERWENT;	
US-PGPUB;   EPO;   JPO;   DERWENT;   IPM TOB   USPAT;			451/\$.ccls.	IBM_TDB	
Second   S	50	155624	"L-shaped"		2004/08/04 09:42
Server   S				US-PGPUB;	
Signature		1		EPO; JPO;	
Second   S				DERWENT;	
147				IBM TDB	
S-PGPUB;   PFO; JFO; JFO; JFO; JFO; JFO; JFO; JFO; J	51	803	"L-shaped" and 451/\$.ccls.	USPĀT;	2004/08/04 09:42
147			•	US-PGPUB;	
147				EPO; JPO;	
147					
147				1	
## wafers substrate substrates semiconductor semiconductors   US-PCPUB; EPG; JPG; EPG; JPG; DERWENT; IBM TDB USPAT; US-PCPUB; EPG; JPG; DERWENT; IBM TDB USPAT; USWAR; USWAR; USPAT; USWAR; USWAR; USWAR	52	147	("L-shaped" and 451/\$.ccls.) and (wafer		2004/08/04 09:45
Semiconductors   SEMICON   SERVENT; IBM TDB   SEMINATE   SEMINAT	"				
Server   S					
Same			bomiconauocoio /		
1109   451/56   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀT 2004/08/04 10:12 USPĀT 2004/08/04 10:15 USPĀT				•	
Second   S	53	1109	451/56		2004/08/04 10:11
Second   S	33	1103	431/30		2004/00/04 10:11
Second   S					
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S-PGPUB;   EPO; JPO; DERWENT; IRM TDB   USPAT;   US-PGPUB;   EPO; JPO; DERWENT; IRM TDB   USPAT;	1		Waratt a maana W in		2004/08/04 10:11
Second   S	54	"	"Scott e. moore.".in.		2004/08/04 10:11
DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;	1				
TBM TDB					
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Second   S		10	, , , , , , , , , , , , , , , , , , ,		2004/00/04 10:11
Second   S	55	10	(scott adj3 moore).in.		2004/08/04 10:11
DERWENT;   IBM TDB					
Secott with moore   Secott with with with with with with with wi					
Second   S				1	
SPEPUB;   EPO; JPO;   DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; JPO; DERWENT;   IBM TDB   US-PGPUB;   EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J					
Second   S	56	267	scott with moore		2004/08/04 10:12
DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT   USPĀT   USPĀT   USPĀT   USPĀT   USPĀT   USPĀT   USPĀT   2004/08/04 10:15   USPĀT   2004/08/04 10:16   USPĀT   2004/08/04 10:17   USPĀT   2004/08/04 10:1		1			
TBM TDB   USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USFAT   USPAT   2004/08/04 10:12   USFAT   2004/08/04 10:15   USFAT   2004/08/04 10:16   USFAT   2004/08/04 10:17   USFAT   2004/08/04 10:					
Secont near moore   USPAT;   2004/08/04 10:12   USPAT;   USPAT   2004/08/04 10:12   USPAT;   USPAT   2004/08/04 10:12   USPAT   2004/08/04 10:12   USPAT   2004/08/04 10:12   USPAT   2004/08/04 10:13   USPAT   2004/08/04 10:14   USPAT   2004/08/04 10:15   USPAT   2004/08/04 10:16   USPAT   2004/08/04 10:17   USPAT				· ·	
Second   S			_		/ /
Second Process	57	248	scott near3 moore		2004/08/04 10:12
DERWENT;   IBM TDB   USPAT;   USPAT   2004/08/04 10:12   USPAT;   USPAT   2004/08/04 10:12   USPAT;   USPAT   2004/08/04 10:12   USPAT   2004/08/04 10:13   USPAT   2004/08/04 10:15   USPAT   2004/08/04 10:16   USPAT   2004/08/04 10:17					
TBM_TDB				· ·	
58       1918       rachuba.xp.       USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPC; DERWENT; IBM TDB USPAT       2004/08/04 10:12         60       1       USPAT; US-PGPUB; EPO; JPC; DERWENT; IBM TDB USPAT       2004/08/04 10:14         61       1       USPAT       2004/08/04 10:15         62       1       USPAT       2004/08/04 10:15         63       1       USPAT       2004/08/04 10:15         64       1       USPAT       2004/08/04 10:15         65       1       USPAT       2004/08/04 10:16         66       1       USPAT       2004/08/04 10:16         67       1       USPAT       2004/08/04 10:16         68       1       USPAT       2004/08/04 10:16         69       1       USPAT       2004/08/04 10:16         70       1       USPAT       2004/08/04 10:16         71       1       USPAT       2004/08/04 10:16         72       1       USPAT       2004/08/04 10:17         73       1       USPAT       2004/08/04 10:17         74       1       USPAT       2004/08/04 10:17	ĺ			1	!
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DERWENT; IBM TDB USPAT; USPAT 2004/08/04 10:12 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17		1			
TBM TDB					i
59 6 (scott near3 moore) and rachuba.xp. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT 2004/08/04 10:14 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT 2004/08/04 10:14 USPAT 2004/08/04 10:15 USPAT 2004/08/04 10:16 USPAT 2004/08/04 10:17 USPAT 2004/08/04 10:17	I	]			
EPO; JPO; DERWENT; IBM_TDB  60	59	6	(scott near3 moore) and rachuba.xp.	1	2004/08/04 10:12
DERWENT; IBM_TDB USPĀT 2004/08/04 10:14 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:15 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:16 USPĀT 2004/08/04 10:17 USPĀT 2004/08/04 10:17					
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